

**VERSIONS WITH MARKINGS TO SHOW CHANGES MADE**

Claim 1 has been amended as follows:

1. (Twice Amended) A printed wiring board comprising an odd number  $n$  of conductive layers which are built up with [an] a same odd number of insulating layers, respectively, and are electrically connected to one another via interconnecting through holes;

wherein [the] a first conductive [later] layer on which an electronic component layer is to be mounted and conducts electric currents in and out of the electronic component; [the] an  $n$ -th conductive layer is an external connecting layer for connecting external connecting terminals which [conducts] conduct electric currents in and out of the printed wiring board; [the] a second to ( $n-1$ )-th conductive layers are current transmitting layers for transmitting internal currents of the printed wiring board; and [the] a surface of [fo] the  $n$ -th conductive layer is covered with [the] an  $n$ -th and outermost insulating layer with external connecting terminals being exposed, and wherein a central insulating layer of the odd number of insulating layers prevents warping from occurring in the printed wiring.

Claim 3 has been amended as follows:

3. (Thrice Amended) A method of manufacturing a printed wiring board having an odd number  $n$  of conductive layers which are built up with [an] a same odd number of insulating layers, respectively, and are electrically connected to one another by first interconnecting through holes, the method comprising the steps of:

interposing the insulating layers between [the] a second to  $n$ -th conductive layers, respectively, and also forming first interconnecting through holes for electrically connecting the conductive layers to one another;

laminating a first prepreg and a copper foil on a surface of the second conductive layer, and [press=bonding] press-bonding a second prepreg on a surface of the n-th conductive layer to form a multilayer substrate having an odd number n of insulating layers, wherein the second to n-th conductive layers are internal layers of the multilayer substrate;

etching the copper foil to form a first conductive layer;

forming second interconnecting through holes in [the] a first insulating layer and forming connecting holes in [the] an n-th insulating layer, respectively;

forming a metal plating film for electrically connecting the first conductive layer with [the] a second conductive layer on the walls of the second interconnecting through holes of the first insulating layer; and

connecting external connecting terminals to [the] a surface of the n-th conductive layer exposed through the first connecting through holes of the n-th insulating layer.

Claim 4 has been amended as follows:

4. (Thrice Amended) A printed wiring board comprising an internal insulating substrate having a conductor circuit formed on a surface thereof, an internal insulating layer laminated on the surface of the internal insulating substrate, and an external insulating layer laminated on a surface of the internal insulating layer, the internal insulating layer and the external insulating layer having an internal conductor circuit and an external conductor circuit, respectively:

wherein the internal insulating layer comprises two or more internal insulating layers of glass cloth-reinforced prepreg containing 30 to 70% by weight of glass cloth.

Claim 7 has been amended as follows:

7. (Amended) A method of manufacturing a printed wiring board having a plurality of conductive layers which are built up [via] with insulating layers respectively and are electrically connected to one another [via] by interconnecting through holes, the method comprising the steps of:

forming conductive layers on a plurality of insulating layers respectively;

laminating and press-bonding the resulting insulating layers to form a multilayer substrate;

irradiating a laser beam on the multilayer substrate at interconnecting through holes-

forming portions to define interconnecting through holes [such that] with bottoms [of the through holes reach] defined by the conductive layers;

covering the walls of the interconnecting through holes with metal plating films; and

fusing solder balls against the interconnecting through holes and filling them with solder.

Claim 11 has been cancelled.

Claim 14 has been cancelled.